

SER WWW

Objective specification

BUJ205AX

Silicon Diffused Power Transistor

GENERAL DESCRIPTION

High-voltage, high-speed planar-passivated npn power switching transistor in the plastic full-pack envelope intended for use in high frequency electronic lighting ballast applications, converters, inverters, switching regulators, motor control systems, etc.

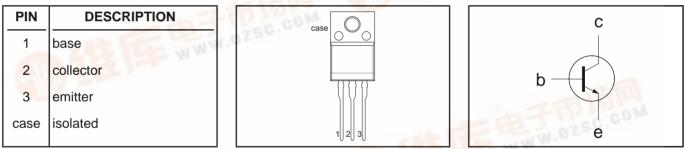
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{CESM}	Collector-emitter voltage peak value	$V_{BE} = 0 V$	-	850	V
V _{CBO}	Collector-Base voltage (open emitter)		-	850	V
V _{CEO}	Collector-emitter voltage (open base)		-	450	V
I _c	Collector current (DC)		-	8	A
I _{CM}	Collector current peak value			12	A
P _{tot}	Total power dissipation	T _{mb} ≤ 25 °C		32	W
V _{CEsat}	Collector-emitter saturation voltage	$T_{mb} \le 25 \degree C$ $I_{C} = 5.0 \text{ A}; I_{B} = 1.0 \text{ A}$	1. 2. 2.	1.5	V
t _f	Fall time	Ic=6A,I _{B1} =1.2A	朝空に	300	μs

PINNING - SOT186A

PIN CONFIGURATION

SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CESM}	Collector to emitter voltage	$V_{BE} = 0 V$	-	850	V
V _{CEO}	Collector to emitter voltage (open base)		-	450	V
V _{CBO}	Collector to base voltage (open emitter)		-	850	V
I _c	Collector current (DC)		-	8	A
I _{CM}	Collector current peak value		1 2 3	12	Α
I _B	Base current (DC)		C - V.	4	A
I _{BM}	Base current peak value	and the file	L OL	6	A
P _{tot}	Total power dissipation	$T_{mb} \leq 25 \degree C$	10.0	32	W
T _{stg}	Storage temperature		-65	150	°C
T_j^{-1}	Junction temperature	an life in the second	-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R _{th j-mb}	Junction to heatsink	with heatsink compound	-	3.95	K/W
R _{th j-a}	Junction to ambient	in free air	60	-	K/W



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ISOLATION LIMITING VALUE & CHARACTERISTIC

 $T_{hs} = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. \leq 65% ; clean and dustfree	-		2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

STATIC CHARACTERISTICS

 T_{mb} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CES}	Collector cut-off current ¹	$V_{BE} = 0 V; V_{CE} = V_{CESMmax}$	-	-	1	mA
ICES		$V_{BE} = 0 V; V_{CE} = V_{CESMmax}$ $V_{BE} = 0 V; V_{CE} = V_{CESMmax};$ $T_i = 125 °C$	-	-	3	mA
I _{EBO}	Emitter cut-off current	$V_{EB} = 9 V; I_{C} = 0 A$	-	-	10	mA
V _{CEOsust}	Collector-emitter sustaining voltage	$I_{B} = 0 \text{ A}; I_{C} = 100 \text{ mA};$ L = 25 mH	450	-	-	V
V _{CEsat}	Collector-emitter saturation voltage	I _C = 5 A; I _B = 1.0 A	-	-	1.5	V
V _{BEsat}	Base-emitter saturation voltage	$I_{\rm C} = 6 \text{ A}; I_{\rm B} = 1.2 \text{ A}$	-	-	1.5	V
h _{FF}	DC current gain	$I_{c} = 10 \text{ mA}; V_{c_{f}} = 5 \text{ V}$	10	-	35	
• =		$I_{\rm C} = 1.0$ A; $V_{\rm CE} = 5$ V	10	-	35	

DYNAMIC CHARACTERISTICS

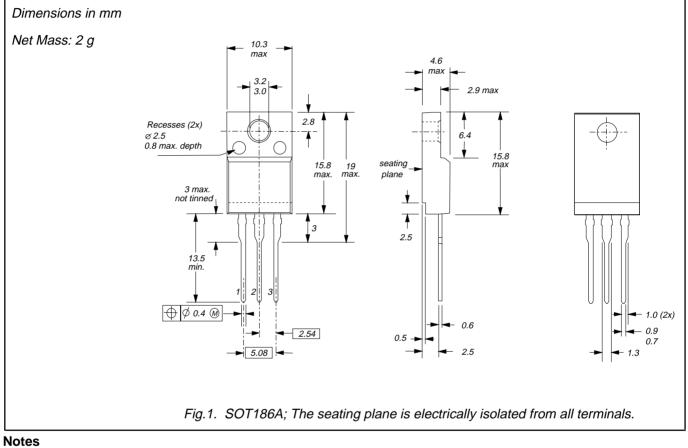
 $T_{mb} = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
	Switching times (resistive load)	$I_{Con} = 6.0 \text{ A}; I_{Bon} = -I_{Boff} = 1.2 \text{ A};$ R ₁ = 75 ohms; V _{BB2} = 4 V;			
t _{on}	Turn-on time		-	1.0	μs
t _s	Turn-off storage time		-	4	μs
t _r	Turn-off fall time		-	0.8	μs
	Switching times (inductive load)	$I_{Con} = 6.0 \text{ A}; I_{Bon} = 1.2 \text{ A}; L_{B} = 1 \mu\text{H};$ -V_{BR} = 5 V			
t,	Turn-off storage time		-	1.5	μs
t _ŕ	Turn-off fall time		-	300	'ns
	Switching times (inductive load)	$I_{Con} = 6.0 \text{ A}; I_{Bon} = 1.2 \text{ A}; L_{B} = 1 \mu\text{H};$ -V _{BB} = 5 V; T _i = 100 °C			
t _s	Turn-off storage time		-	2.5	μs
t	Turn-off fall time		-	300	ns

¹ Measured with half sine-wave voltage (curve tracer).

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MECHANICAL DATA



Refer to mounting instructions for F-pack envelopes.
Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status				
Objective specification	bjective specification This data sheet contains target or goal specifications for product development.			
Preliminary specification	reliminary specification This data sheet contains preliminary data; supplementary data may be published late			
Product specification	This data sheet contains final product specifications.			
Limiting values				
or more of the limiting val operation of the device at	in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one ues may cause permanent damage to the device. These are stress ratings only and these or at any other conditions above those given in the Characteristics sections of aplied. Exposure to limiting values for extended periods may affect device reliability.			
• •	ation is given, it is advisory and does not form part of the specification.			
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